

## **BULD118D-1**

# HIGH VOLTAGE FAST-SWITCHING NPN POWER TRANSISTOR

- INTEGRATED ANTIPARALLEL COLLECTOR- EMITTER DIODE
- HIGH VOLTAGE CAPABILITY
- LOW SPREAD OF DYNAMIC PARAMETERS
- MINIMUM LOT-TO-LOT SPREAD FOR RELIABLE OPERATION
- VERY HIGH SWITCHING SPEED

#### **APPLICATIONS:**

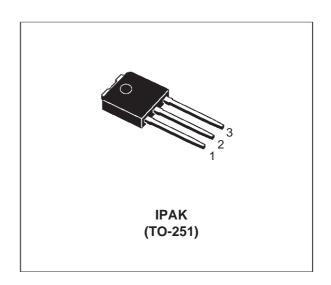
- ELECTRONIC BALLASTS FOR FLUORESCENT LIGHTING
- FLYBACK AND FORWARD SINGLE TRANSISTOR LOW POWER CONVERTERS

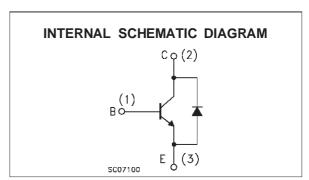
#### **DESCRIPTION**

The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds and medium voltage capability.

It uses a Cellular Emitter structure with planar edge termination to enhance switching speeds while maintaining the wide RBSOA.

The device is designed for use in lighting applications and low cost switch-mode power supplies.





#### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage (V <sub>BE</sub> = 0)	700	V
Vceo	Collector-Emitter Voltage (I <sub>B</sub> = 0)	400	V
$V_{EBO}$	Emitter-Base Voltage ( $I_C = 0$ )	9	V
Ic	Collector Current	2	Α
I <sub>CM</sub>	Collector Peak Current (tp < 5 ms)	4	Α
lΒ	Base Current	1	Α
I <sub>BM</sub>	Base Peak Current (t <sub>p</sub> < 5 ms)	2	Α
P <sub>tot</sub>	Total Dissipation at T <sub>c</sub> = 25 °C	20	W
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
Tj	Max. Operating Junction Temperature	150	°C

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## THERMAL DATA

R <sub>thj-</sub>	case Thermal	Resistance	Junction-Case	Max	6.25	°C/W
R <sub>thj</sub> -	<sub>amb</sub> Thermal	Resistance	Junction-Ambient	Max	100	°C/W

## **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25$ °C unless otherwise specified)

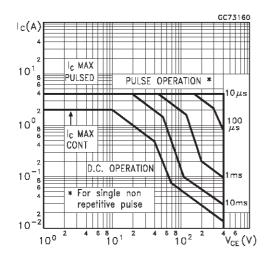
Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
I <sub>CES</sub>	Collector Cut-off Current (V <sub>BE</sub> = 0)	V <sub>CE</sub> = 700 V V <sub>CE</sub> = 700 V	T <sub>j</sub> = 125 °C			100 500	μA μA
V <sub>EBO</sub>	Emitter-Base Voltage	I <sub>E</sub> = 10 mA		9			V
V <sub>CEO(sus)</sub>	Collector-Emitter Sustaining Voltage	I <sub>C</sub> = 100 mA	L = 25 mH	400			V
I <sub>CEO</sub>	Collector-Emitter Leakage Current	V <sub>CE</sub> = 400 V				250	μА
V <sub>CE(sat)</sub> *	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 0.5 A I <sub>C</sub> = 1 A I <sub>C</sub> = 2 A	$I_B = 0.1 A$ $I_B = 0.2 A$ $I_B = 0.4 A$			0.5 1 1.5	V V V
V <sub>BE(sat)*</sub>	Base-Emitter Saturation Voltage	I <sub>C</sub> = 0.5 A I <sub>C</sub> = 1 A I <sub>C</sub> = 2 A	I <sub>B</sub> = 0.1 A I <sub>B</sub> = 0.2 A I <sub>B</sub> = 0.4 A			1.0 1.2 1.3	V V V
h <sub>FE</sub> *	DC Current Gain	I <sub>C</sub> = 10 mA I <sub>C</sub> = 0.5 A I <sub>C</sub> = 2 A	V <sub>CE</sub> = 5 V V <sub>CE</sub> = 5 V V <sub>CE</sub> = 5 V	10 10 8		50	
t <sub>r</sub> t <sub>f</sub> t <sub>s</sub>	RESISTIVE LOAD Rise Time Fall Time Storage Time group A group B	$VCC = 125 V$ $I_{B1} = 0.4 A$ $t_p = 30 \mu s$	I <sub>C</sub> = 2 A I <sub>B2</sub> = -0.2 A	1.4	0.7 0.3	0.5 2.1 2.75	μs μs μs μs
ts t <sub>f</sub>	INDUCTIVE LOAD Storage Time Fall Time	I <sub>C</sub> = 1 A V <sub>BE</sub> = -5 V V <sub>clamp</sub> = 300 V	I <sub>B1</sub> = 0.2 A L = 50 mH		0.8 0.10		μs μs
$V_{F}$	Diode Forward Voltage	IC = 1 A				2.5	V

\* Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %

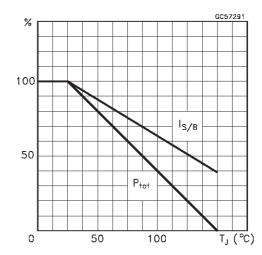
Note: Product is pre-selected in storage time (GROUP A and GROUP B). SGS-THOMSON reserves the right to ship either groups according to production availability. Please contact your nearest SGS THOMSON MICROELECTRONICS sales office for delivery details.

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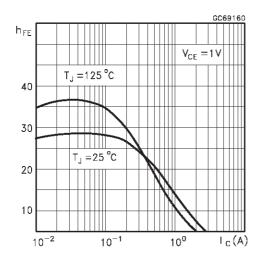
### Safe Operating Areas



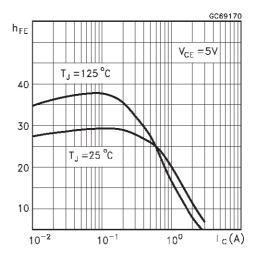
# Derating Curve



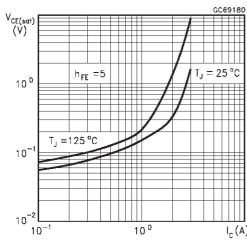
DC Current Gain



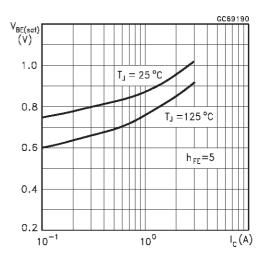
DC Current Gain



Collector Emitter Saturation Voltage

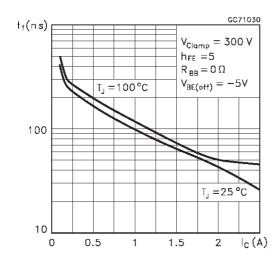


Base Emitter Saturation Voltage

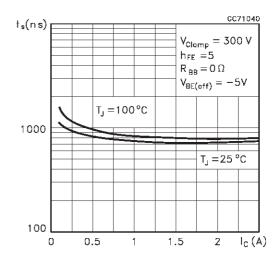


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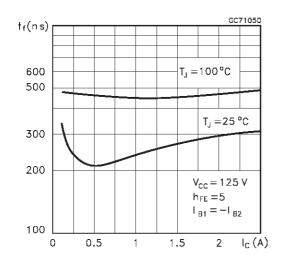
#### Inductive Fall Time



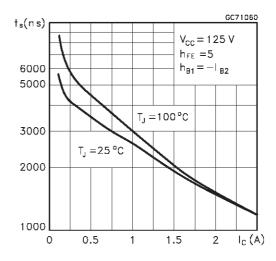
## Inductive Storage Time



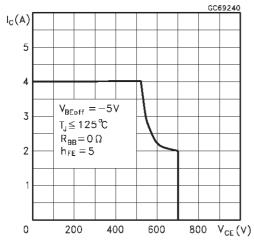
#### Resistive Fall Time



Resistive Load Storage Time



### Reverse Biased SOA



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Figure 1: Inductive Load Switching Test Circuit.

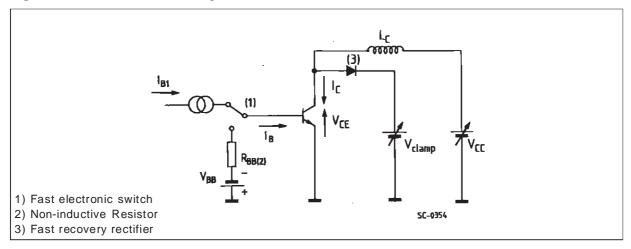
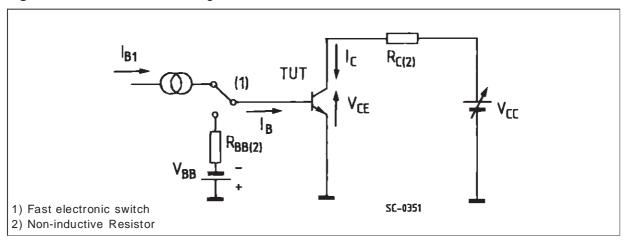
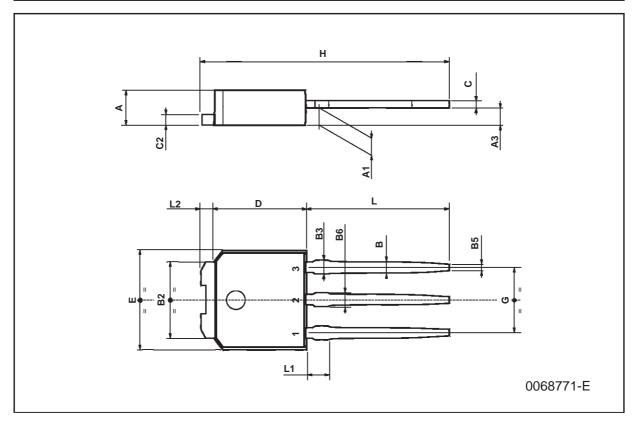


Figure 2: Resistive Load Switching Test Circuit.



# TO-251 (IPAK) MECHANICAL DATA

DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	2.2		2.4	0.086		0.094	
A1	0.9		1.1	0.035		0.043	
А3	0.7		1.3	0.027		0.051	
В	0.64		0.9	0.025		0.031	
B2	5.2		5.4	0.204		0.212	
В3			0.85			0.033	
B5		0.3			0.012		
B6			0.95			0.037	
С	0.45		0.6	0.017		0.023	
C2	0.48		0.6	0.019		0.023	
D	6		6.2	0.236		0.244	
Е	6.4		6.6	0.252		0.260	
G	4.4		4.6	0.173		0.181	
Н	15.9		16.3	0.626		0.641	
L	9		9.4	0.354		0.370	
L1	0.8		1.2	0.031		0.047	
L2		0.8	1		0.031	0.039	



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